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Akazawa et al.

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(54) **RETAINING RING FOR SUBSTRATE**

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(73) Assignee: **EBARA CORPORATION**, Tokyo (JP)

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(52) **U.S. Cl.**
USPC **D15/138**; D13/182

(58) **Field of Classification Search**
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CPC H01J 37/3414; H01J 37/3423; H01L 21/02631; H01L 2221/68363; H01L 2224/75186-75189; H01L 21/67742; H01L 21/0226; H01L 21/02263; H01L 21/02266; H01L 21/02269; H01L 21/02271; F16J 7/00; E04D 13/14; C23C 14/3407; C23C 14/35
See application file for complete search history.

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(57) **CLAIM**

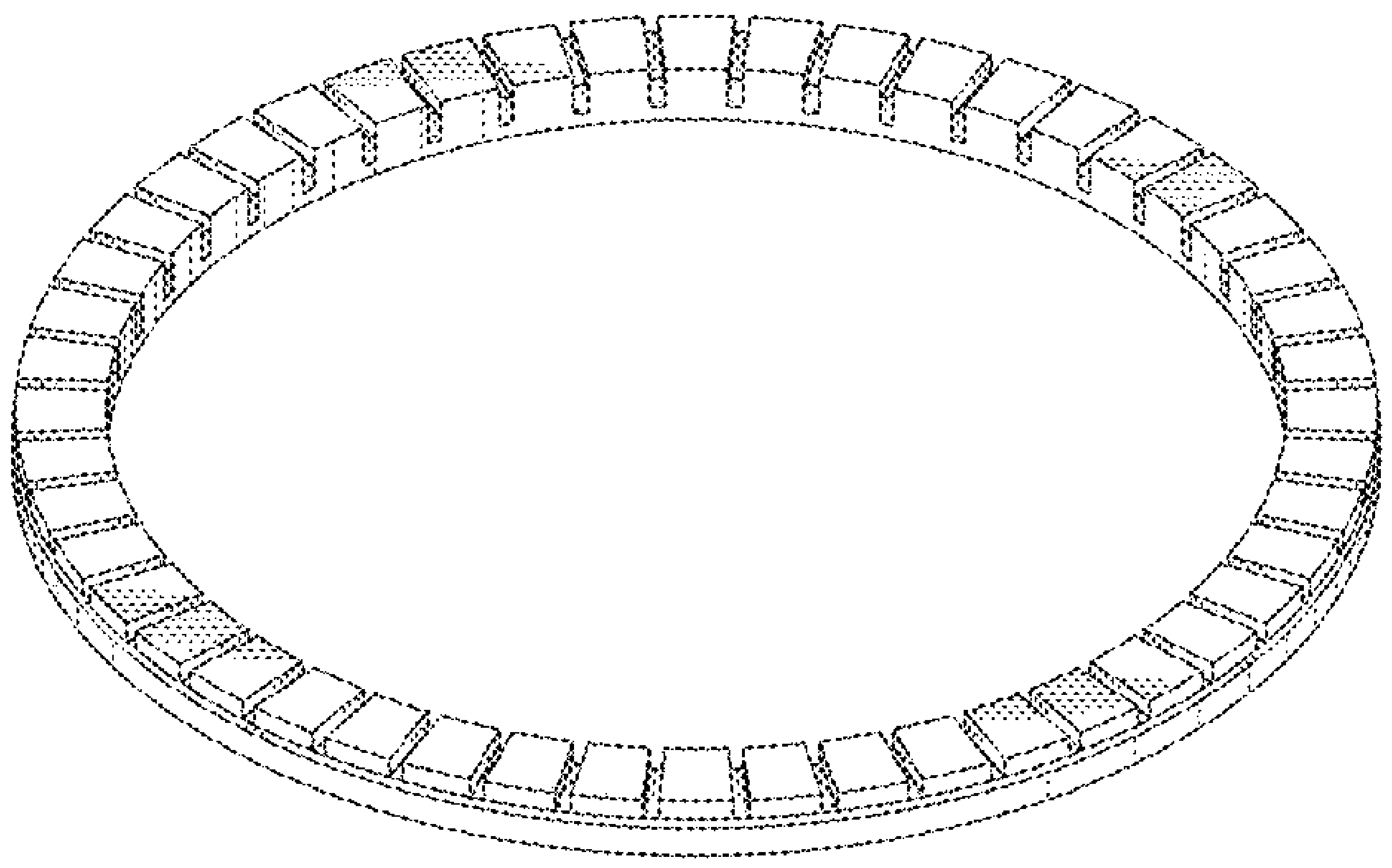
The ornamental design for a retainer ring for substrate, as shown and described.

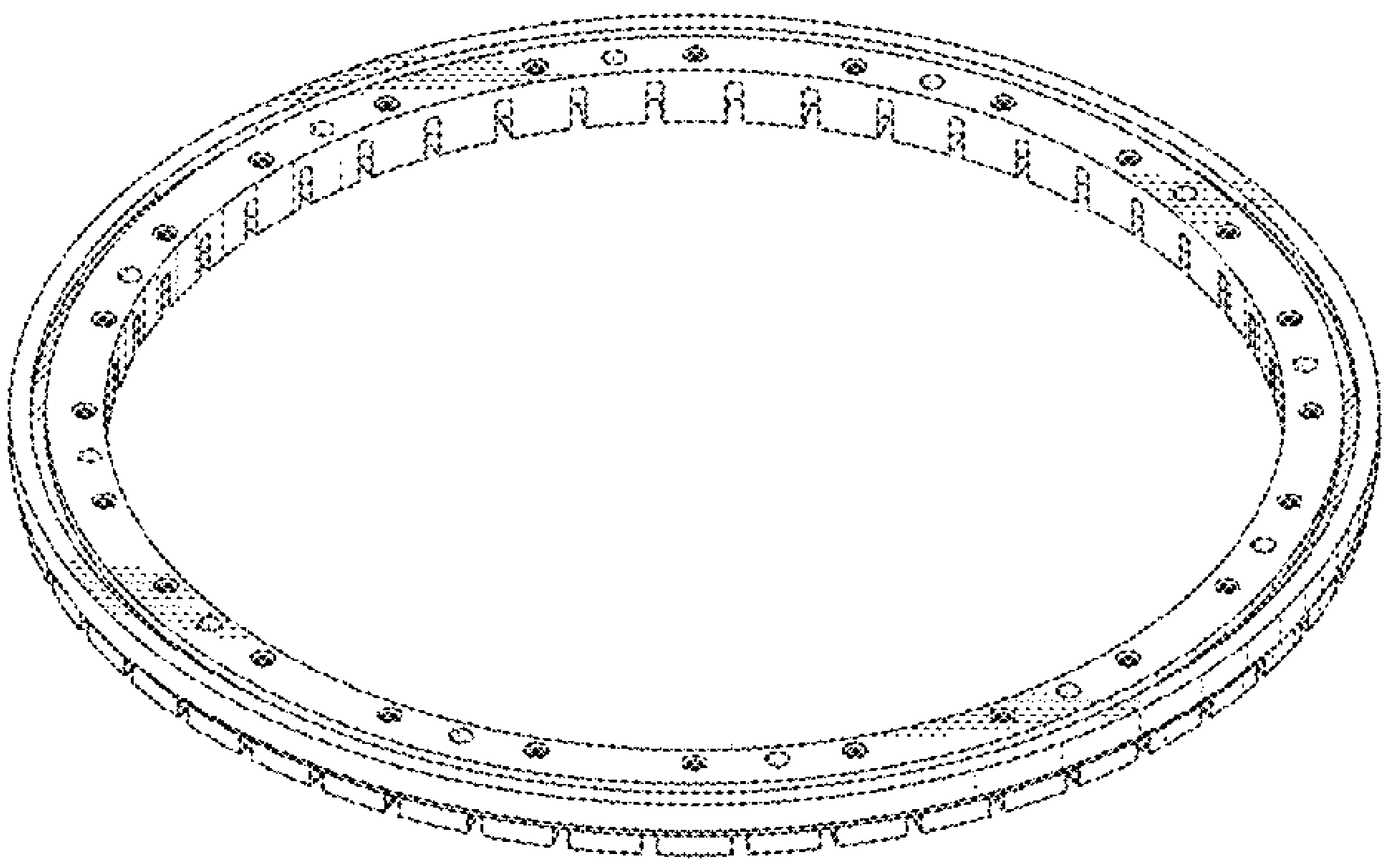
DESCRIPTION

1. Retaining ring for substrate
1.1 : Perspective
1.2 : Perspective
1.3 : Bottom
1.4 : Top
1.5 : Front
1.6 : Cross sectional
1.7 : Cross sectional
1.8 : Cross sectional

This article is used to hold a substrate in a ring and polish one side of the substrate during the polishing process of wafers and other substrates in the manufacture of semiconductors and other products; the rear view, right side view, and left side view are all represented identically to the front view.

1 Claim, 8 Drawing Sheets





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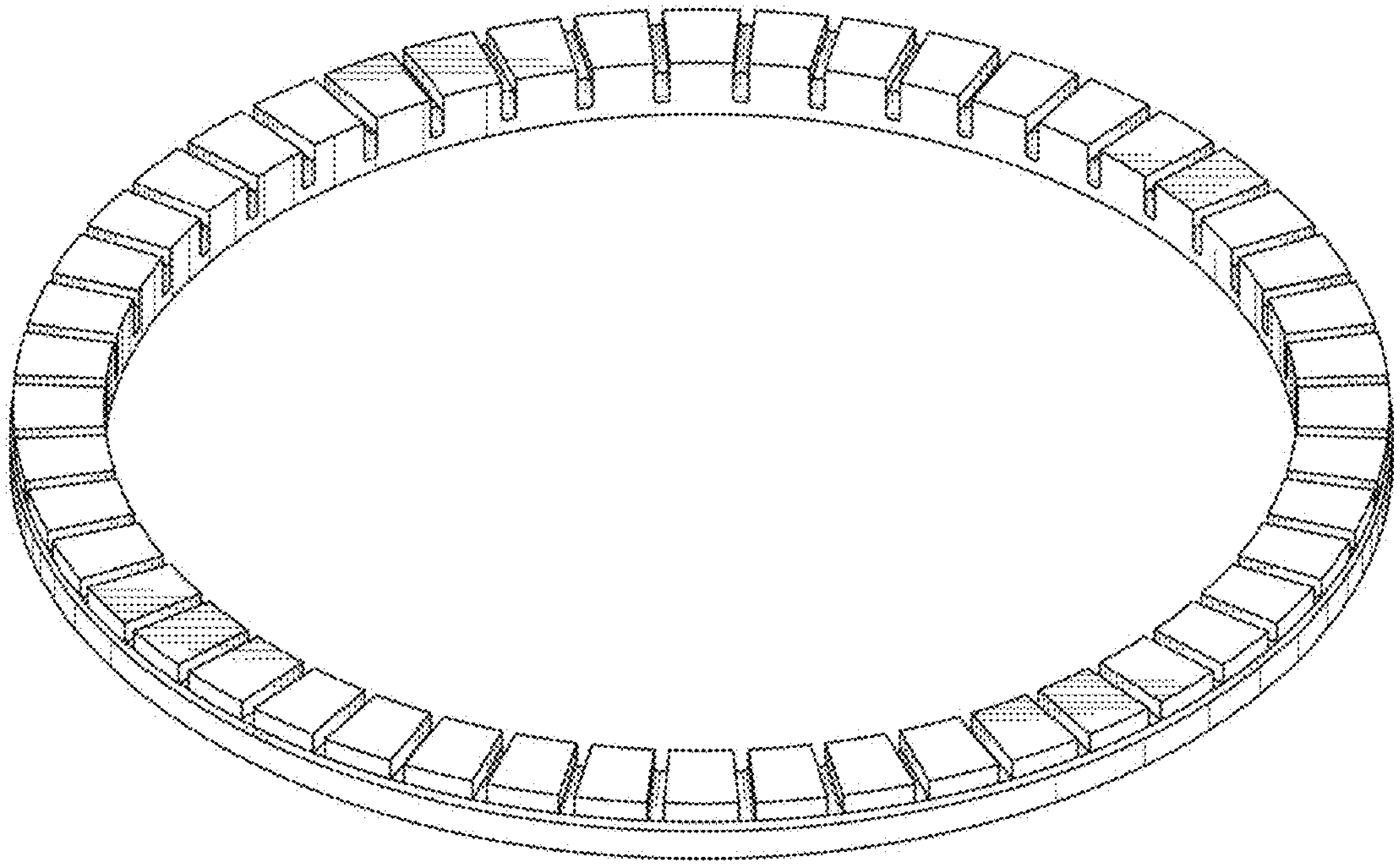

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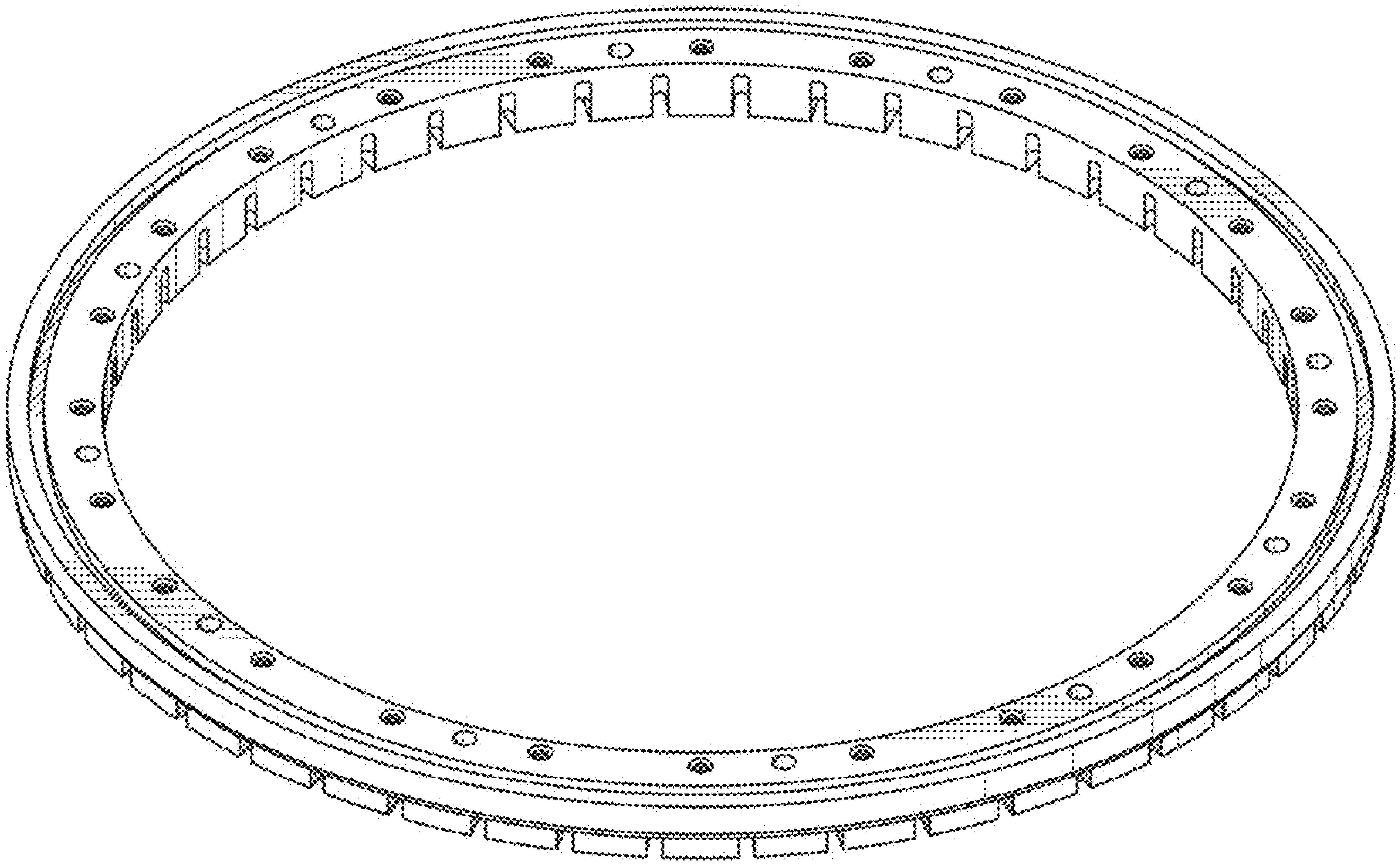

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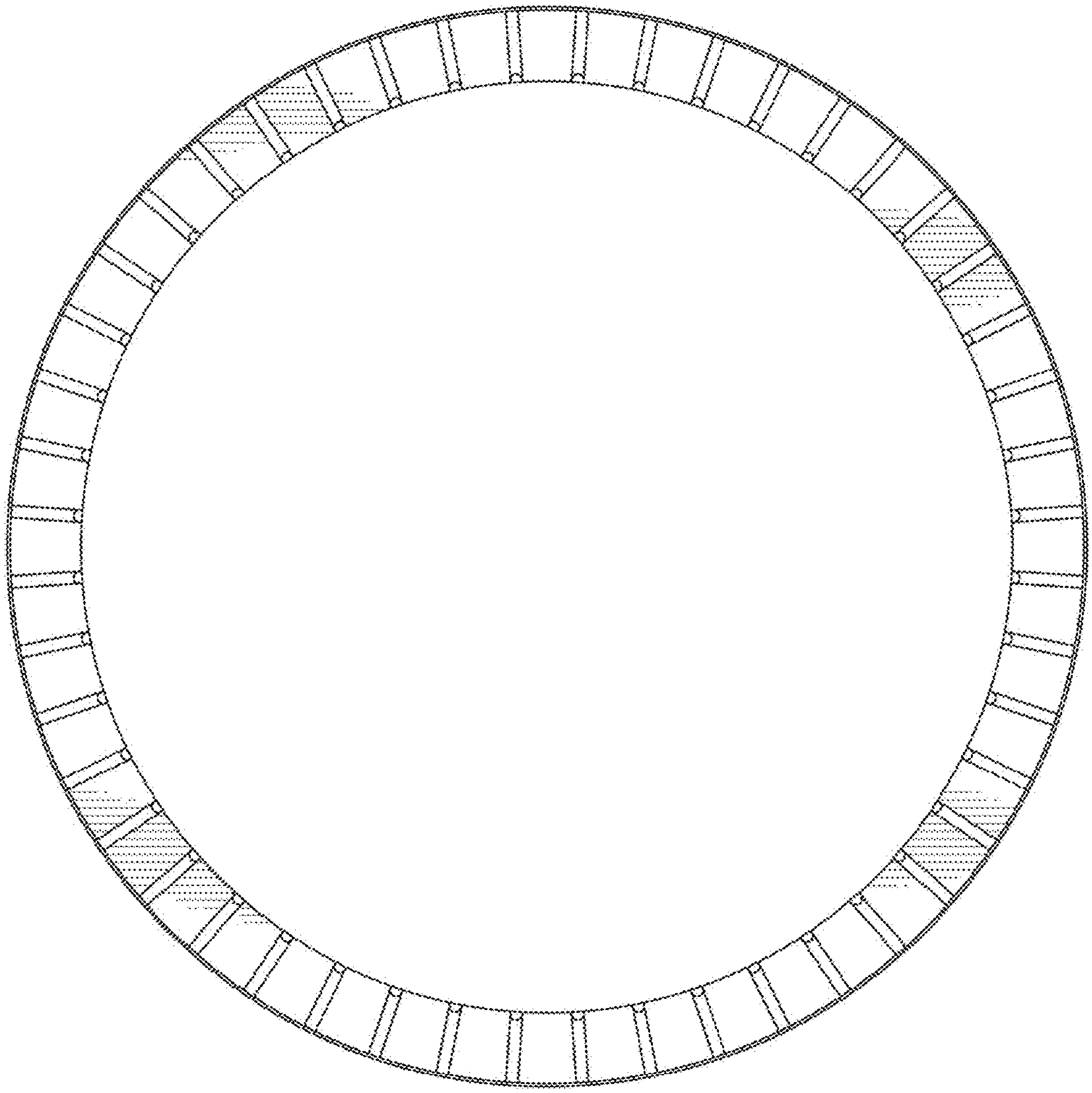

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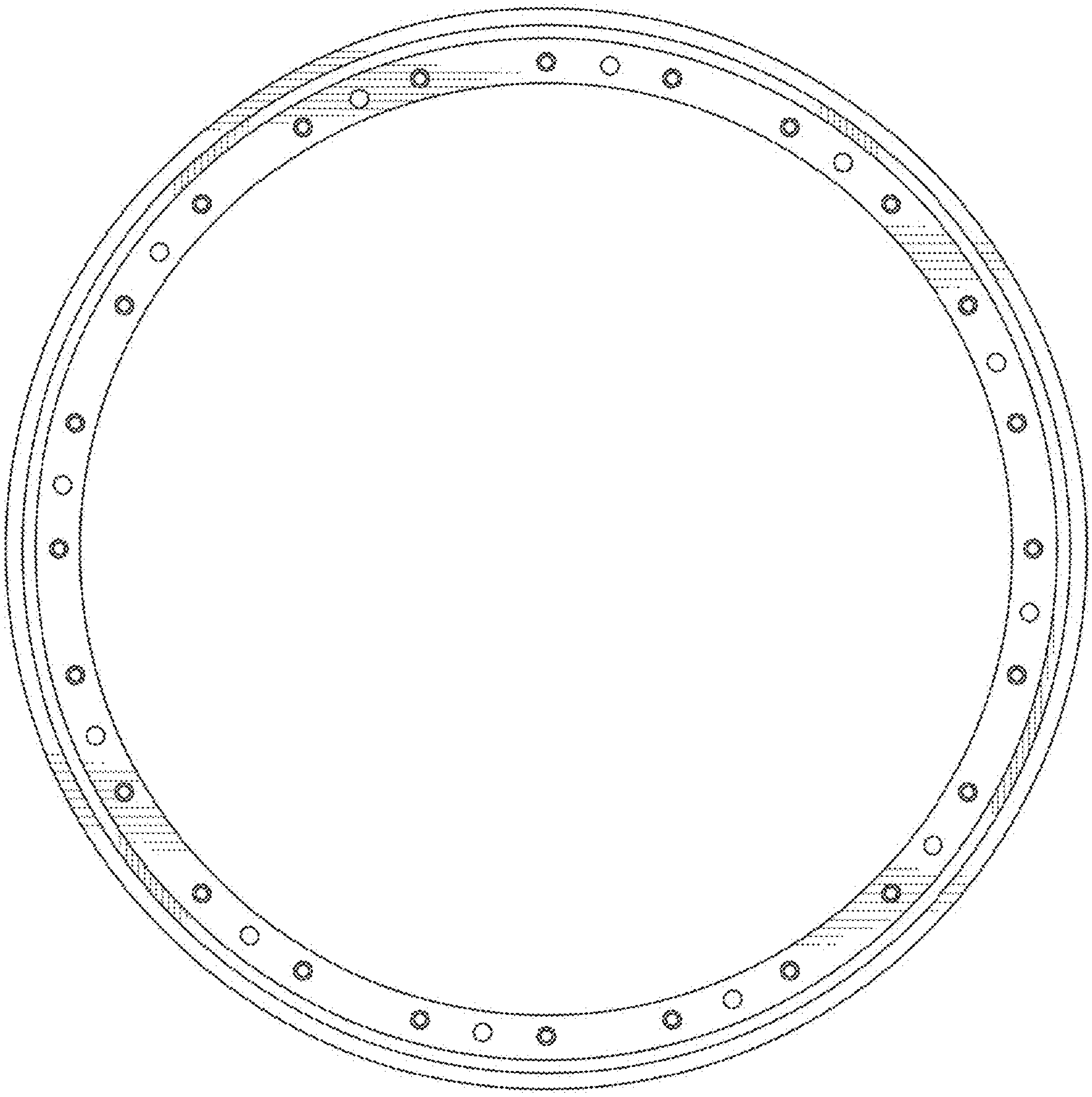

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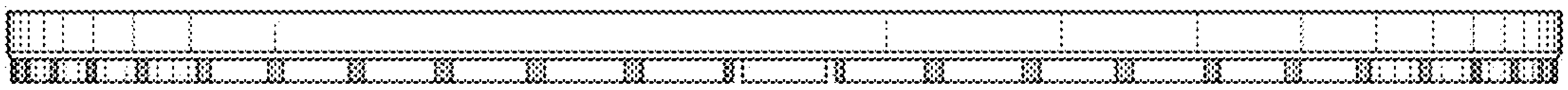

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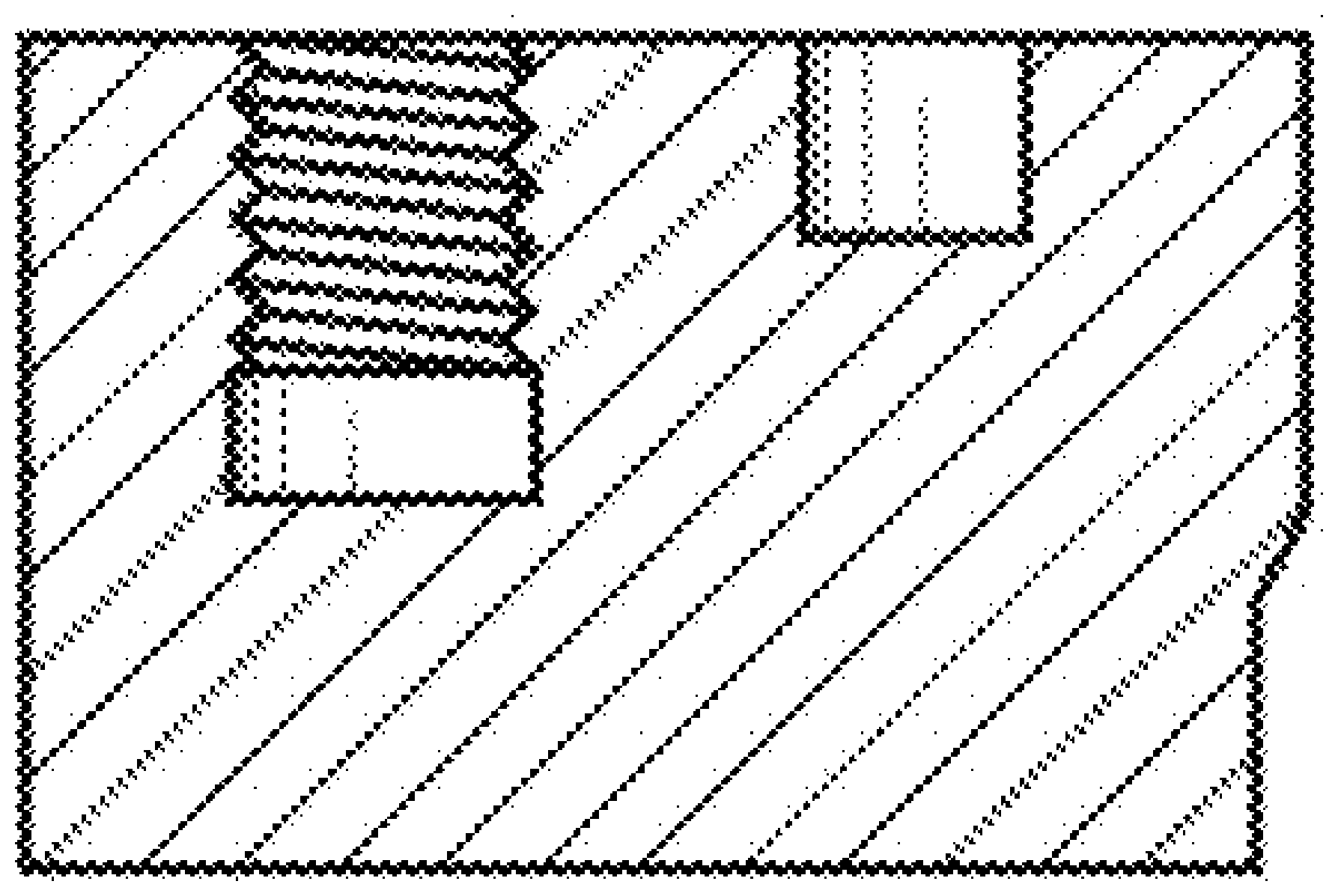

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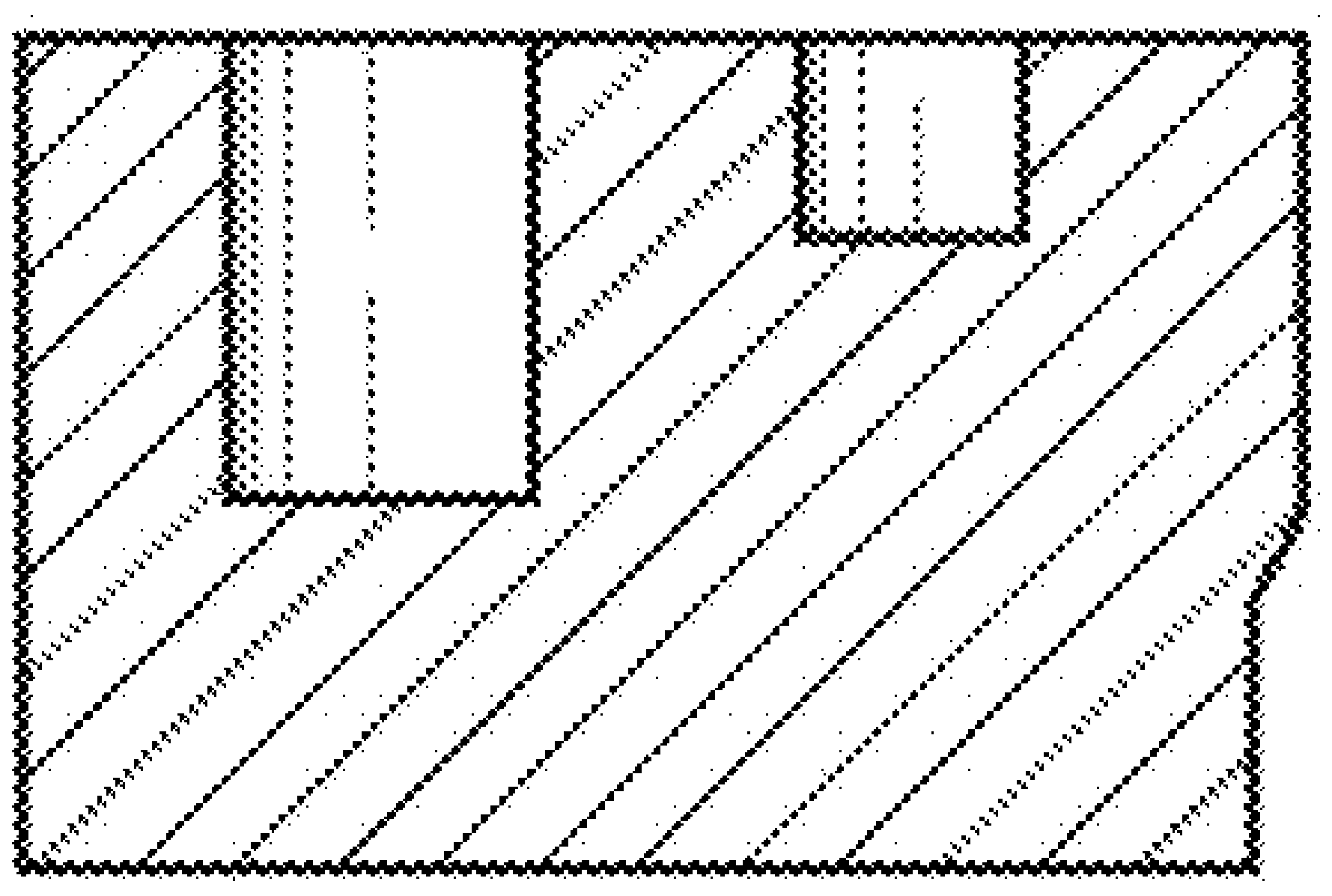

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